



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



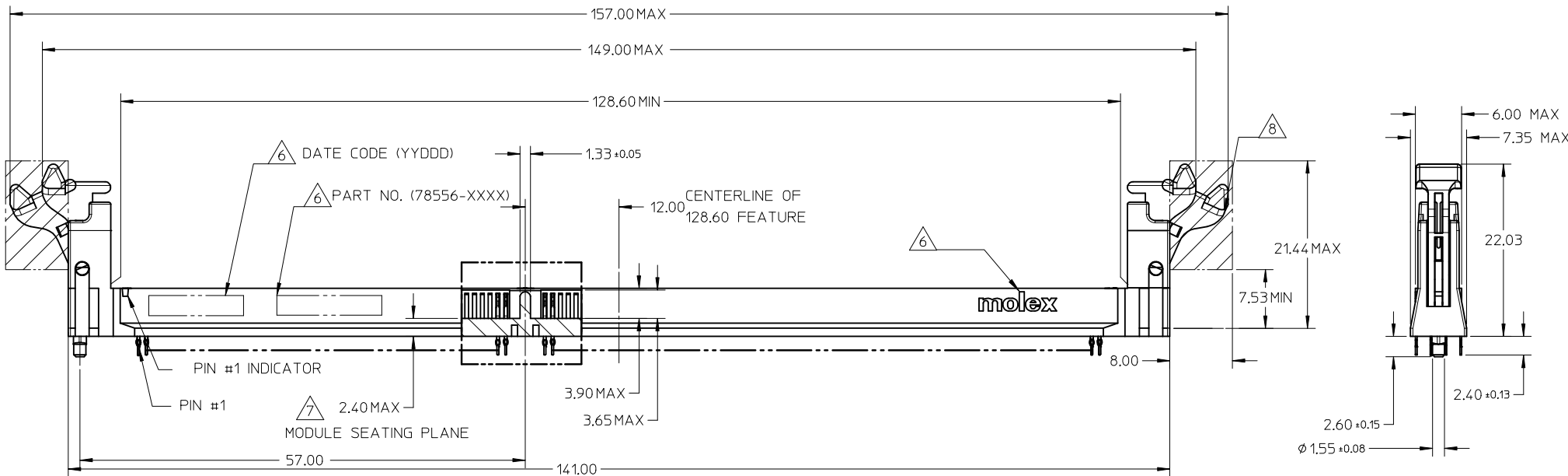
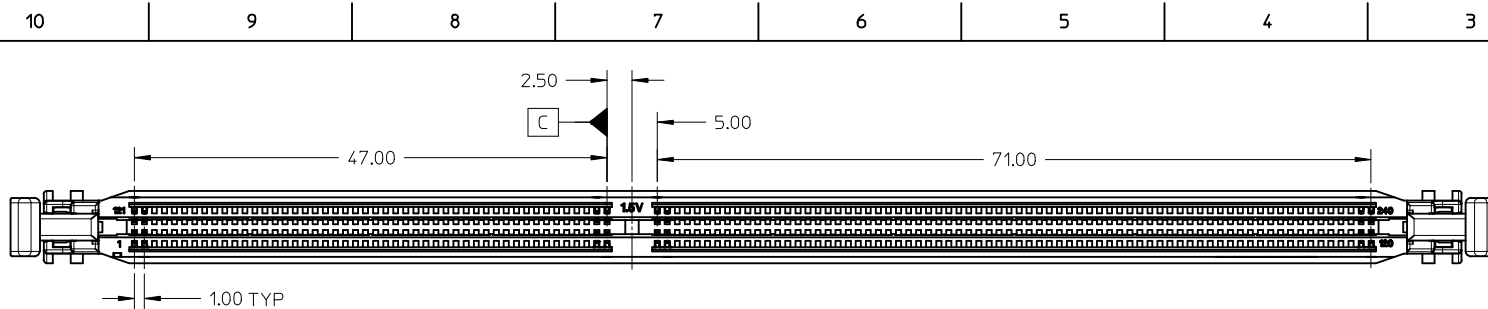
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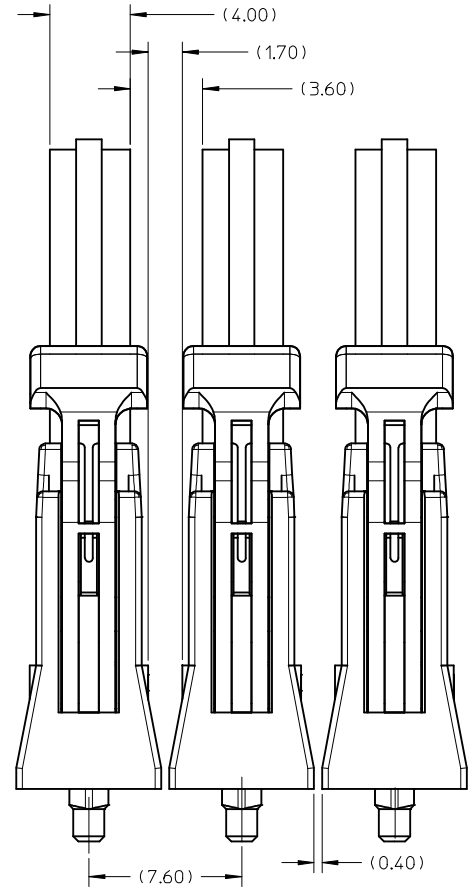
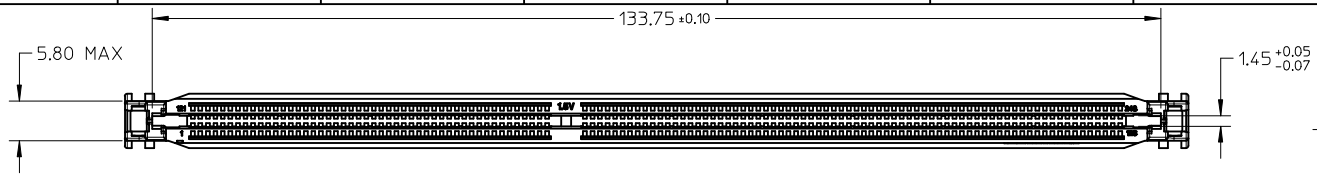


NOTES:

- MATERIAL:  
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - SEE TABLE  
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 04V-0, COLOR - SEE TABLE  
TERMINAL - COPPER ALLOY
- FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
- PRODUCT SPECIFICATION: PS-78556-001
- PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
- CARD SLOT ACCEPTS 1.27±/-0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
- MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
- MODULE SEATING PLANE FROM TOP OF PCB
- KEEP OUT ZONE RESERVED FOR LATCH

AMEND PCB DIM EC NO: S2013-0772 DRWN: CCTEH 2012/11/19 CHKD: CGTAN 2013/06/03 APPR: SHLENI 2013/06/03	QUALITY SYMBOLS F <sub>A</sub> =0 F <sub>E</sub> =0 F <sub>P</sub> =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			mm	INCH	DRAWN BY CCTEH	DATE 2011/04/26	TITLE 1MM DDR3 LSP ST. LATCH 240CKTS VERT. PF LLLCR	
		4 PLACES	± ---	± ---	CHECKED BY CGTAN	DATE 2011/06/22		
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2011/06/29		
			2 PLACES	± 0.20	± ---			
			1 PLACE	± ---	± ---			
			0 PLACE	±	±			
			ANGULAR ± 1 °		MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78556-002	SHEET NO. 1 OF 5
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

10 9 8 7 6 5 4 3 2 1

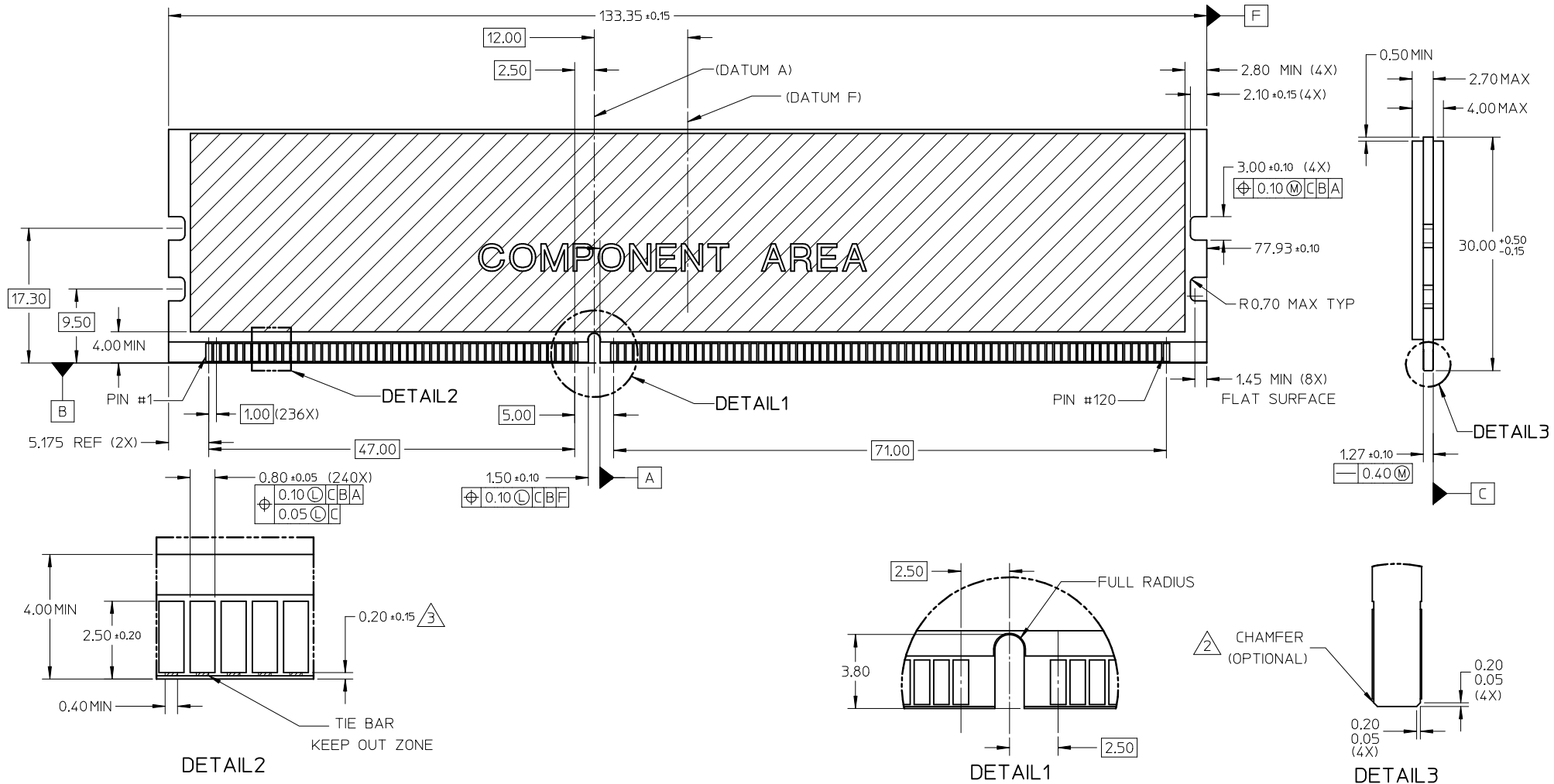


MINIMUM ROW TO ROW SPACING RECOMMENDATION  
(USING 4.00MM MODULE CARD)

AMEND PCB DIM EC NO: S2013-0772 DRWN: CCTEH 2012/11/19 CHKD: CGTAN 2013/06/03 APPR: SHLENI 2013/06/03	DESCRIPTION REV	QUALITY SYMBOLS F <sub>A</sub> =0 F <sub>G</sub> =0 F <sub>P</sub> =0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
			mm	INCH	DRAWN BY CCTEH	DATE 2011/04/26	TITLE 1MM DDR3 LSP ST. LATCH 240CKTS VERT. PF LLLCR		
2			4 PLACES	± ---	± ---	CHECKED BY CGTAN	DATE 2011/06/22	molex	SHEET NO. 2 OF 5
			3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2011/06/29		
			2 PLACES	± 0.20	± ---	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78556-002	
			1 PLACE	± ---	± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
			0 PLACE	±	±				
			ANGULAR ± 1 °						
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						

9 8 7 6 5 4 3 2 1

MODULE CARD  
 DDR3 DUAL IN-LINE MEMORY MODULE FAMILY 1.00MM CONTACT CENTERS  
 (JEDEC MO-269, ISSUE B, MAY 06)

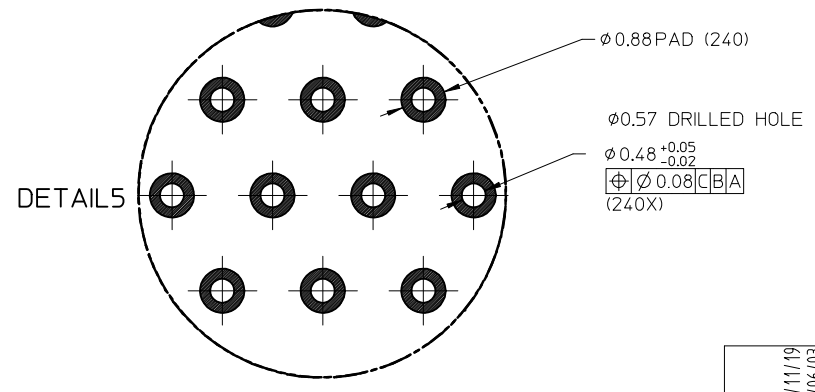
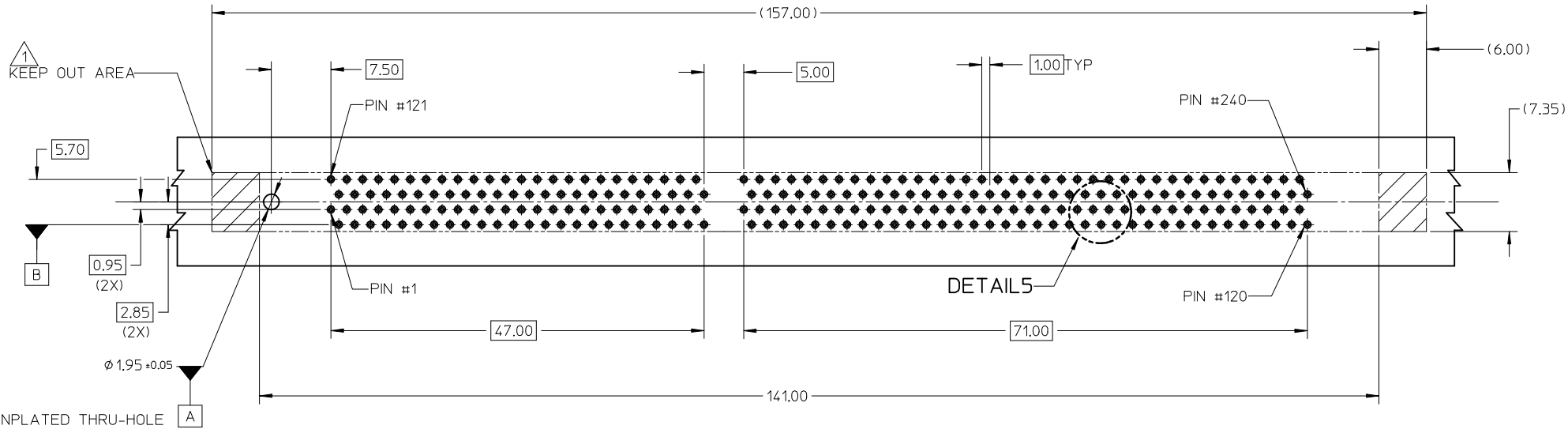


NOTES:

- RECOMMENDED PLATING FOR CONTACT PADS:  
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN  
 OVER 2.00 MICROMETERS NICKEL  
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING  
 OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC  
 CONTACT GRADE CORROSIVE BARRIER LUBRICANT
- CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
- LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE  
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

AMEND PCB DIM IEC NO: S2013-0772 2012/11/19 DRW:CCTEH 2013/06/03 CHYKD:CGTAN APPR:SHLENI 2013/06/03	QUALITY SYMBOLS $F_A=0$ $F_B=0$ $F_C=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm	INCH	DRAWN BY CCTEH	DATE 2011/04/26	TITLE	1MM DDR3 LSP ST. LATCH 240CKTS VERT. PF LLLCR		
		4 PLACES	± ---	± ---	CHECKED BY CGTAN	DATE 2011/06/22				
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2011/06/29				
2 PLACES	± 0.20	± ---	MATERIAL NO.		DOCUMENT NO.	SD-78556-002				
1 PLACE	± ---	± ---	SEE TABLE		SHEET NO.			3 OF 5		
0 PLACE	±	±	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1



NOTES:  
 1. KEEP-OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

AMEND PCB DIM	2	REV
EC NO: S2013-0772	DRW: CCTEH	2012/11/19
CHKD: CGTAN	2013/06/03	
APPR: SHLENI	2013/06/03	

QUALITY SYMBOLS	DESCRIPTION
$F_A=0$	
$F_G=0$	
$F_P=0$	


GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm INCH
4 PLACES	± --- ± ---
3 PLACES	± --- ± ---
2 PLACES	± 0.20 ± ---
1 PLACE	± --- ± ---
0 PLACE	± ±
ANGULAR ± 1 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	
DRAWN BY	DATE
CCTEH	2011/04/26
CHECKED BY	DATE
CGTAN	2011/06/22
APPROVED BY	DATE
SHLENI	2011/06/29
MATERIAL NO.	
SEE TABLE	
SIZE	A3

SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
TITLE		
1MM DDR3 LSP ST. LATCH 240CKTS VERT. PF LLLCR		
DOCUMENT NO.		SHEET NO.
SD-78556-002		4 OF 5
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

9 8 7 6 5 4 3 2 1

PART NO.	KEY POS.	RECOMMENDED PCB THICKNESS	PLATING OPTION		LATCH COLOUR	HOUSING COLOUR
			CONTACT AREA	TAIL AREA		
78556-5001	CENTER (1.5V)	3.00	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	BLACK	BLACK
78556-5051					BLUE	BLUE
78556-5061					NATURAL	NATURAL

<b>AMEND PCB DIM</b> EC NO: S2013-0772 DRWN: CTEH 2012/11/19 CHKD: CGTAN 2013/06/03 APPR: SHLENI 2013/06/03	QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE <b>MM ONLY</b>	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			mm	INCH	DRAWN BY CTEH	DATE 2011/04/26	TITLE 1MM DDR3 LSP ST. LATCH 240CKTS VERT. PF LLLCR	
		4 PLACES	± ---	± ---	CHECKED BY CGTAN	DATE 2011/06/22		
		3 PLACES	± ---	± ---	APPROVED BY SHLENI	DATE 2011/06/29		
2 PLACES	± 0.20	± ---	MATERIAL NO.		DOCUMENT NO.	SHEET NO.		
1 PLACE	± ---	± ---	SEE TABLE		SD-78556-002	5 OF 5		
0 PLACE	±	±	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			